Call for papers

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Manuscript Deadline: May 1, 2020

Interfacial Stability in Multi-component Systems

Papers are invited for this special topic covering interfacial bonding, interfacial stability, reaction kinetics, phase formation and characterization, and complex interfacial phenomena in various applied fields, including advanced microelectronics packaging, semiconductor systems, thermoelectric modules, energy materials and other related interfacial systems.

Original research papers should be 3,000-6,000 words with up to 8 figures maximum; review papers should be 6,000-10,000 words with up to 15 figures maximum.

Detailed author instructions are available at:
http://www.tms.org/AuthorTools/

Keywords for this topic: Alloy Phases; Electronic Materials

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If you are interested in submitting a paper, upload your manuscript at
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